RTX-113

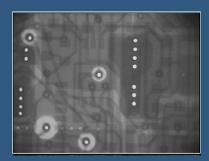
A unique X-ray inspection system, designed for rapid, reliable inspection of both multi-layer and assembled printed circuit boards



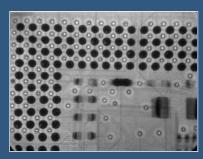
Our RTX-113 system meets all your needs for inspecting BGA packages, including those that contain dense metal heat sinks that require a higher voltage X-ray source to clearly identify and troubleshoot production faults. The cabinet design permits easy integration into even the busiest production environments, and is totally upgradeable. Recommended for lead free inspection requirements.

Technologies Inc.

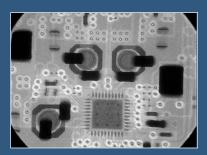
Multi-Layer PCB Applications include Drill Registration of Multilayer PC Boards, BGA micro BGA, QFN, Cables, and Medical Devices



Drill Registration of Multilayer PC Board



BGA Inspection



QFN Inspection



Cable Inspection

Specifications

- Dimensions: 44"H x 42"W x 24"D (1066.8mm x 1117.6mm x 609.8mm)
- Operating Voltage: 120v, 60hz or 220v, 50hz
- Contrast Resolution: Can resolve .001 gold wire
- Spatial Resolution: 20 lp/mm (with MicroTech™ option, up to 100 lp/mm)
- Anode Voltage: 52 kv or optional 80 kv
- Anode Current: 50 or 90 microamps
- Magnification: 15x geometric to 50x optical
- Focal Spot to Image Plane Distance: 4-6 inches
- X-ray Activation Mode: Foot Pedal or PC Controlled

Options

- Image Processing
- MicroTechTM 10-micron X-ray Source (225X) Motorized X-Y positioner
- BGA and Void measurement software
- Motorized X-Y Positioner with joystick controller
- Variable Angle Viewing allowing 45 degree viewing

